



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	\pm	3.00	3.30
A ₁	2.30	2.56	2.82
A ₂	2.10	2.20	2.30
D/E	35.00 BSC		
D ₁ /E ₁	33.00 REF		
e	1.27BSC		
øb	0.51	0.54	0.57
ccc	\pm	\pm	0.35
ddd	\pm	\pm	0.30
eee	\pm	\pm	0.15
M	27		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. SOLDER COLUMN: HIGH TEMP. SOLDER WITH COPPER RIBBON Pb(80%)/Sn(20%)

27X27-COLUMN CERAMIC CGA, 1.27MM PITCH (CG717)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
1/18/06	1.0	Initial Xilinx release.